DOCUMENT CHANGE REQUEST

DCR number 410	Changes required for: Qualification	Originator: BUSSENOT Jean-Paul
Date: 2008/06/03	Date sent: 2008/06/03	Organisation:
Status: IMPLEMENTED		

Title:	Resistors fixed film chips, based on type P HR		
Number:	4001/023	Issue:	3

Other documents affected:

Page:

Totally rewritten to implement changes resulting from the modification of 4001

Paragraph:

Totally rewritten to implement changes resulting from the modification of 4001

Original wording:

Proposed wording:

See attached draft (colour only refer to changes from previous draft presented to PSWG to illustrate the result of changes to 4001).
The wording take into consideration up-dating of the ESCC format in line with new proposed 4001 and previous input received from the technical writer on this document.
This DCR superseedes approved DCR 366 not yet implemented.

Justification:

Up-dating resulting from changes implemented in ESCC 4001

Attachments:

4001023DraftH.pdf, null

Modifications:

Proposed text for modified version of DCR410 on 4001/023 Issue 3 to fully replace the original DCR contents:

.....
Paragraphs and Pages Affected
Specification 4001/023 issue 3 is re-written as issue 4 to incorporate changes, resulting from the proposed modification of 4001 issue 1 (per currently pending DCR409) including implementation of Failure Rate Level requirements, as summarised herein (see Attached for proposed issue 4 Draft H).

The layout, format and general content of the proposed 4001/023 issue 4 is based closely on the re-written ESCC Detail Specifications under current ESCC 9000 issue 4. The technical content of the proposed ESCC 4001/023 issue 4 remains closely based on the original ESCC 4001/023 issue 3.

.....
Other Documents Affected N/A

.....
Proposed Wording of Change
Total reformat of this Detail Specification (from the range of various ESCC Detail Specifications, 4001/xxx, for resistors under Generic Specification No. 4001) as part of the ongoing conversion to the ESCC format.

In addition the specification is amended to include the requirements applicable to the specification of a Failure Rate Level for components consistent with the proposed new generic 4001 issue 2 and new ESCC Basic Specification No. 94 - FAILURE RATE LEVEL SAMPLING PLANS AND PROCEDURES, as proposed for implementation into the ESCC system by pending DCR409. Currently as advised by Vishay/F only new Variants 09 to 12 are planned to be available with an approved failure rate level (as is specified in the Vishay/F Appendix).

See below for summary of changes, also see attached proposed Issue 4 Draft H.

Note: known support for active procurement against this specification includes the following Manufacturer:
Vishay SA Sfernice/France (ESCC QPL listed with qualified Variants 01, 02, 03 plus willing to support procurement of all other variants)

Summary of changes to the current format, layout and content is as follows:

1. Rewording and restructure of various sections and paragraphs of the specification, plus other editorial changes based on the layout and editorial content of other Detail Specifications already converted to ESCC format.

2. Addition of the Failure Rate Level Letter to the definition of the ESCC Component Number (in para. 1.4.1)

3. Addition of new Variants 09 to 12 (in para 1.4.2)

4. Addition of notes that state Variants 05 to 08 are not suitable for solder assembly methods (i.e. Solderability testing is not applicable to Variants 05 to 08)(in paras 1.4.2 Note 6, 1.5 Note 4, 2.1.1.2, 2.7 Note 1).

5. Clarification that, for components with a specified temperature coefficient of TC=+/-5ppm/C, a TC=+/-10ppm/C applies over the full operating temperature range (in para 1.4.2 Note 4).

6. In the Maximum Ratings table amend "Insulation Voltage" to be "Isolation Voltage" (to be consistent with ESCC4001 & ESCC2134000)(in para 1.5)

7. Figure 1 Parameter Derating Requirements moved to be a note to the Maximum Ratings table (in para 1.5).

8. Para. 4.4.1 Case, clarified to refer to the "resistive element" rather than "Alumina substrate" (in para 1.7.1).

9. New para 2.5 for Resistance to Soldering Heat test is added.

10. Insulation Resistance test is added to Table 2 but is guaranteed but not tested during screening (in para 2.6.1).

11. Para 4.6.2 & Table 3. High & Low Temp Electrical's: change the applied sampling to be a fixed sample of 5 mounted components from the total production lot (to be consistent with new proposed generic 4001 issue 2)(in para 2.6.2).

12. Table 3 (new para 2.6.2)
TC limits for 5ppm/C components added to Table 3 for temp ranges -55C to +155C.
TC limits for 5ppm/C components for temp range +22C to +70C corrected to be +/- 0.026%

13. Table 4 is deleted.

14. Figure 5 is deleted.

15. Table 6, Delete drying "Procedure I" reference from Solderability & Resistance to Soldering Heat (to be consistent with ESCC 4001)(in para 2.7).

16. Table 6. 8000hour test references added to Operating Life applicable to Failure Rate Endurance Testing only (in para 2.7)

17. Vishay/F Appendix
The following deviations are added to the Vishay/F appendix:
- Dimension Check (screening level test) specified as guaranteed but not tested.
- Permanence of Marking (Qual level test) specified as guaranteed but not tested.
- Burn-in during Screening is not applicable for Failure Rate Level specified versions of Variants 09 to 12. For these components Burn-in is effectively replaced by Overload with a GONOGO measurement of change in resistance.

.....
Justification (see also change details for each item above):

1, 6, 7, 9, 10, 11, 13, 14, 15; Part of the ongoing activity of conversion of ESA/SCC specifications to the ESCC format. Amendments are made to the format and presentation to be consistent with the various other ESCC Detail Specifications, already converted to ESCC format, as well as the proposed ESCC Generic Specification No. 4001 issue 2 (per DCR409)

2, 3, 16, 17; Implementation of Failure Rate Level as requested by Vishay/F to be consistent with DCR409 on ESCC4001 issue 1 and new ESCC Basic Specification No. 94.

17; As requested by Manufacturer Vishay/F.

4, 5, 8; Clarification provided by Vishay/F & CNES.

12; Minor amendments to make the testing consistent with the specified requirements.

Justification:
as above

Approval signature:



Date signed:

2008-06-03

RESISTORS, FIXED, CHIP, THIN FILM

BASED ON TYPE PHR

ESCC Detail Specification No. 4001/023

Issue 4 Draft H	November 2008

Document Custodian: European Space Agency - see https://escies.org

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DOCUMENTATION CHANGE NOTICE

(Refer to https://escies.org for ESCC DCR content)

DCR No.	CHANGE DESCRIPTION
410	Specification updated to incorporate editorial and technical changes per DCR.

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1. GENERAL

1.1 SCOPE

This specification details the ratings, physical and electrical characteristics and test and inspection data for the component type variants and/or the range of components specified below. It supplements the requirements of, and shall be read in conjunction with, the ESCC Generic Specification listed under Applicable Documents.

1.2 APPLICABLE DOCUMENTS

The following documents form part of this specification and shall be read in conjunction with it:

(a) ESCC Generic Specification No. 4001.

1.3 TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESCC Basic Specification No. 21300 shall apply.

1.4 THE ESCC COMPONENT NUMBER AND COMPONENT TYPE VARIANTS

1.4.1 The ESCC Component Number

The ESCC Component Number shall be constituted as follows:

Example: 400102301R2490P1

- Detail Specification Reference: 4001023
- Component Type Variant Number: 01 (as required)
- Failure Rate Level Letter: R (as applicable; see Note 1)
- Characteristic code: Resistance Value (249Ω): 2490 (as required)
- Characteristic code: Resistance Tolerance (±0.02%): P (as required)
- Characteristic code: Temperature Coefficient ($\pm 10 \times 10^{-6}/^{o}C$): 1 (as required)

NOTES:

1. Failure rate level letter shall be as defined in ESCC Basic Specification No. 2xxxx. When a failure rate level is not applicable the letter shall be omitted.

1.4.1.1 Characteristics and/or Ratings Codes

Characteristics and/or ratings to be codified as part of the ESCC Component Number shall be as follows:

(a) Resistance Value expressed by means of the following codes in accordance with ESCC Basic Specification No. 21700. The unit quantity shall be ohm (Ω):

Resistance Value (Ω)	Code
XX.X	XXRX
XXX	XXX0
XXX 10^1	XXX1
XXX 10^2	XXX2

Resistance Value (Ω)	Code
XXX 10^3	XXX3
XXX 10^4	XXX4

(b) Resistance Tolerance expressed by the following codes in accordance with ESCC Basic Specification No. 21700:

Tolerance (± %)	Code Letter
0.01	L
0.02	P
0.05	W
0.1	B

(c) Temperature Coefficient expressed by the following codes:

Temperature Coefficient ($\pm 10^{-6}/^{o}C$)	Code
5	0
10	1
25	2

1.4.2 Component Type Variants and Range of Components

The component type variants and range of components applicable to this specification are as follows:

Variant Number	Style (Note 1)	Resistance Range R_n (Notes 2, 3)		Tolerance (± %) (Note 3)	Temperature Coefficient TC ($\pm 10^{-6}/^{o}C$) (Note 4)	Limiting Element Voltage (V)	Stability Class (± %) (Note 5)	Terminal Material and Finish	Weight max (g)
		Min (Ω)	Max (MΩ)						
01	0603	50	0.2	0.01, 0.02, 0.05, 0.1	5, 10, 25	35	0.15	E4	0.003
02	0805	50	0.25	0.01, 0.02, 0.05, 0.1	5, 10, 25	75	0.15	E4	0.004
03	1206	50	1	0.01, 0.02, 0.05, 0.1	5, 10, 25	100	0.15	E4	0.01
04	2010	50	3	0.01, 0.02, 0.05, 0.1	5, 10, 25	150	0.15	E4	0.03
05	0603	50	0.2	0.01, 0.02, 0.05, 0.1	5, 10, 25	35	0.15	E2 (Note 6)	0.003
06	0805	50	0.25	0.01, 0.02, 0.05, 0.1	5, 10, 25	75	0.15	E2 (Note 6)	0.004
07	1206	50	1	0.01, 0.02, 0.05, 0.1	5, 10, 25	100	0.15	E2 (Note 6)	0.01
08	2010	50	3	0.01, 0.02, 0.05, 0.1	5, 10, 25	150	0.15	E2 (Note 6)	0.03
09	0603	100	0.261	0.05, 01	10, 25	50	0.25	E4	0.003
10	0805	100	0.301	0.05, 01	10, 25	100	0.25	E4	0.004
11	1206	100	1	0.05, 01	10, 25	150	0.25	E4	0.01
12	2010	100	3.01	0.05, 01	10, 25	200	0.25	E4	0.03

NOTES:

1. See Physical Dimensions.
2. Critical resistance is as follows:

Variant Number	Critical Resistance (kΩ)
01, 05	12.25
02, 06	45
03, 07	40
04, 08	45
09	25
10	80
11	90
12	80

3. Available tolerances and resistance values are as follows:

Resistance R_n (Ω)	Variant Number	Available Tolerance (± %)	Available Resistance Values
$50 \leq R_n < 100$	01 to 08	0.05 and 0.1	Any value in the resistance range to 3 significant figures
$100 \leq R_n < 250$	01 to 08	0.02, 0.05, 0.1	
	09 to 12	0.05, 0.1	
$R_n \geq 250$	01 to 08	0.01, 0.02, 0.05, 0.1	
	09 to 12	0.05, 0.1	

4. The temperature ranges applicable to the temperature coefficients are as follows.
   – $\pm 5 \times 10^{-6}/^{o}C$ over $T_{amb}=+22^{o}C$ to $+70^{o}C$, together with $\pm 10 \times 10^{-6}/^{o}C$ over $T_{amb}=-55^{o}C$ to $+155^{o}C$.
   – $\pm 10 \times 10^{-6}/^{o}C$ over $T_{amb}=-55^{o}C$ to $+155^{o}C$.
   – $\pm 25 \times 10^{-6}/^{o}C$ over $T_{amb}=-55^{o}C$ to $+155^{o}C$.
5. Stability class refers to the limit of Change in Resistance, after 2000 hour Operating Life, specified in Intermediate and End-Point Electrical Measurements.
6. Variants 05 to 08 are not suitable for solder assembly methods. They shall be assembled using glue or wire bond techniques.

1.5 MAXIMUM RATINGS

The maximum ratings shall not be exceeded at any time during use or storage.
Maximum ratings shall only be exceeded during testing to the extent specified in this specification and when stipulated in Test Methods and Procedures of the ESCC Generic Specification.

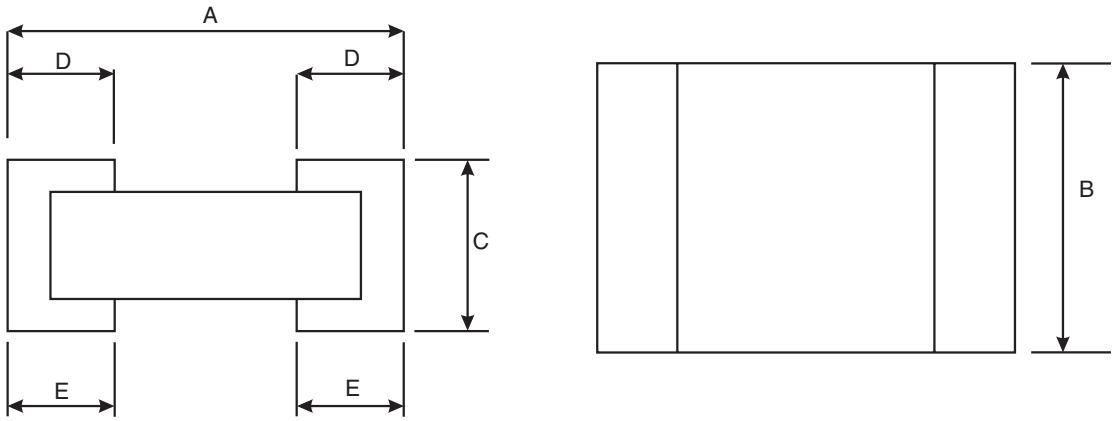
Characteristics	Variant Number	Style	Symbols	Limits	Units	Remarks
Rated Dissipation	01, 05, 09 02, 06, 10 03, 07, 11 04, 08, 12	0603 0805 1206 2010	P_n	100 125 250 500	mW	Note 1

Characteristics	Variant Number	Style	Symbols	Limits	Units	Remarks
Limiting Element Voltage	01, 05 02, 06 03, 07 04, 08 09 10 11 12	0603 0805 1206 2010 0603 0805 1206 2010	U_L	35 75 100 150 50 100 150 200	V	-
Rated Voltage	All	All	U_R	$\sqrt{(P_n x R_n)}$	V	Note 2
Isolation Voltage	01, 05, 09 02, 06, 10 03, 07, 11 04, 08, 12	0603 0805 1206 2010	U_i	100 200 300 300	Vrms	-
Operating Temperature Range	All	All	T_{op}	-55 to +155	^oC	T_{amb}
Storage Temperature Range	All	All	T_{stg}	-55 to +155	^oC	-
Soldering Temperature	01 to 04, 09 to 12	All	T_{sol}	+260	^oC	Notes 3, 4

NOTES:

1. At $T_{amb} \leq +70^oC$. For $T_{amb} > +70^oC$ derate linearly to 0W at $T_{amb} = +155^oC$.
2. Shall never exceed Limiting Element Voltage. R_n=Rated Resistance.
3. Duration 10 seconds maximum.
4. Not applicable to Variants 05 to 08.

1.6 PHYSICAL DIMENSIONS



Variant Number	Style	Dimensions (mm)							
		A		B		C		D	
		Min	Max	Min	Max	Min	Max	Min	Max
01, 05, 09	0603	1.39	2.16	0.62	1.01	0.25	1.02	0.25	0.51
02, 06, 10	0805	1.78	2.55	1.14	1.53	0.25	1.02	0.25	0.51
03, 07, 11	1206	2.87	3.64	1.47	1.86	0.25	1.02	0.25	0.51
04, 08, 12	2010	4.95	5.72	2.41	2.8	0.25	1.02	0.35	0.85

1.7 MATERIALS AND FINISHES

1.7.1 Body

The resistive element deposited on the alumina substrate shall be covered with a suitable coating.

1.7.2 Terminations

The terminal material and finish shall be as specified in Component Type Variants and Range of Components in accordance with the requirements of ESCC basic Specification No. 23500.

2. REQUIREMENTS

2.1 GENERAL

The complete requirements for procurement of the components specified herein are as stated in this specification and the ESCC Generic Specification. Permitted deviations from the Generic Specification, applicable to this specification only, are listed below.

Permitted deviations from the Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalent to the ESCC requirement and do not affect the component's reliability, are listed in the appendices attached to this specification.

2.1.1 Deviations from the Generic Specification

2.1.1.1 Deviations from Screening Tests (Chart F3)

(a) Para. 8.3.2, Room Temperature Electrical Measurements after Burn-in: for ±0.01% and ±0.02% tolerances, components with a resistance outside the limits of Room Temeprature Electrical Measurements after burn-in but remaining within a ±0.03% tolerance shall be rejected, but not counted for PDA.

2.1.1.2 Deviations from Qualification and Periodic Tests (Chart F4)

(a) Para. 8.9, Vibration: Not applicable.
(b) Para. 8.14, Solderability: Not applicable to Variants 05 to 08.

2.2 MARKING

The marking of all components delivered to this specification shall be in accordance with the requirements of ESCC Basic Specification No. 21700. When the component is too small to accommodate all of the marking specified, as much as space permits shall be marked and the marking information, in full, shall accompany each component in its primary package.

The information to be marked and the order of precedence, shall be as follows:

(a) The ESCC qualified components symbol (for ESCC qualified components only).
(b) The ESCC Component Number.
(c) Traceability information.

2.3 OVERLOAD

The test conditions for Overload, tested as specified in the ESCC Generic Specification, shall be as follows:

Voltage:	$\sqrt{(6.25P_n x R_n)}$ or $2U_L$, whichever is less.
Duration:	2s minimum.

2.4 ROBUSTNESS OF TERMINATIONS - SUBSTRATE BENDING TEST

The test conditions for the Substrate bending Test, tested as specified in the ESCC Generic Specification, shall be as follows:

Number of bends:	10.
Deflection:	2mm (for Variants 01, 02, 03, 05, 06, 07, 09, 10, 11) 1mm (for Variants 04, 08, 12)
Duration:	5±1s

2.5 RESISTANCE TO SOLDERING HEAT

The test conditions for Resistance to Soldering Heat, tested as specified in the ESCC Generic Specification, shall be as follows:

Temperature:	260°C
Duration:	$10^{(+0-1)}$s

2.6 ELECTRICAL MEASUREMENTS AT ROOM, HIGH AND LOW TEMPERATURES

2.6.1 Room Temperature Electrical Measurements

The measurements shall be performed at T_{amb}=+22 ±3°C.

Characteristics	Symbols	ESCC 4001 Test Method and Conditions	Tolerance (± %)	Limits		Units
				Min	Max	
Resistance	R_A	Para. 8.3.1.1	0.01	0.9999 R_n	1.0001 R_n	Ω
			0.02	0.9998 R_n	1.0002 R_n	
			0.05	0.9995 R_n	1.0005 R_n	
			0.1	0.999 R_n	1.001 R_n	
Insulation Resistance	R_I	Para. 8.3.1.2 V=100V Note 1	All	1000	-	MΩ

NOTES:
1. Guaranteed but not tested during Screening Tests.

2.6.2 High and Low Temperatures Electrical Measurements

Characteristics	Symbols	ESCC 4001 Test Method and Conditions		Limits		Unit
				Min	Max	
Resistance Change between -55 (+3-0)°C and +22 ± 3°C	$\Delta R_A/R_A$	Para. 8.3.1.1	TC = ±5 x 10^{-6}/°C TC = ±10 x 10^{-6}/°C TC = ±25 x 10^{-6}/°C	-0.08 -0.08 -0.2	+0.08 +0.08 +0.2	%
Resistance Change between +155 (+0 -3)°C and +22 ± 3°C	$\Delta R_A/R_A$	Para. 8.3.1.1	TC = ±5 x 10^{-6}/°C TC = ±10 x 10^{-6}/°C TC = ±25 x 10^{-6}/°C	-0.136 -0.136 -0.34	+0.136 +0.136 +0.34	%
Resistance Change between +70 (+0 -3)°C and +22 ± 3°C	$\Delta R_A/R_A$	Para. 8.3.1.1	TC = ±5 x 10^{-6}/°C	-0.026	+0.026	%

NOTES:
1. The measurements shall be performed on a sample of 5 components selected from the total production lot. The resistors shall be mounted as specified in the ESCC Generic Specification.

2.7 INTERMEDIATE AND END-POINT ELECTRICAL MEASUREMENTS

The resistors shall be mounted as specified in the ESCC Generic Specification.

Unless otherwise specified, the measurements shall be performed at T_{amb}=+22 ±3°C.

Unless otherwise specified the test methods and test conditions shall be as per the corresponding test defined in Room Temperature Electrical Measurements.

Test Reference per ESCC No. 4001	Characteristics	Symbols	Limits		Units
			Min	Max	
Rapid Change of Temperature	Resistance	R_A	Record Values		
Robustness of Terminations					
Resistance to Soldering Heat	Change in Resistance	$\Delta R_A/R_A$	$\pm(0.05 + 0.05\Omega x100/R_n)$		%
Solderability (Note 1)					
Climatic Sequence					
Initial Measurements (Procedure 1)	Resistance (after drying)	R_A	Record Values		
Final Measurements	Change in Resistance	$\Delta R_A/R_A$	$\pm(0.1 + 0.05\Omega x100/R_n)$		%
	Insulation Resistance (V_T=100V)	R_I	1000	-	MΩ
Operating Life					
Initial Measurement (0 hour)	Resistance	R_A	Record Values		
Intermediate Measurements (1000 hours)	Change in Resistance	$\Delta R_A/R_A$	$\pm(0.1 + 0.05\Omega x100/R_n)$		%
Intermediate/ Final Measurements (2000 hours)	Change in Resistance	$\Delta R_A/R_A$			%
	Variants 01 to 08		$\pm(0.15 + 0.05\Omega x100/R_n)$		
	Variants 09 to 12		$\pm(0.25 + 0.05\Omega x100/R_n)$		
	Insulation Resistance (V_T=100V)	R_I	1000	-	MΩ
Final Measurements (8000 hours) (Note 2)	Change in Resistance	$\Delta R_A/R_A$	$\pm(1 + 0.05\Omega x100/R_n)$		%

NOTES:
1. Solderability is applicable to Variants 01 to 04 and 09 to 12 only.
2. Applicable to Failure Rate Endurance Testing only.

2.8 BURN-IN CONDITIONS

Characteristics	Symbols	Test Conditions	Units
Ambient Temperature	T_{amb}	+70±5	^{o}C
Test Voltage	V_T	$\sqrt{(P_n x R_n)}$ or U_L whichever is less	V

NOTES:

1. After Burn-in, the components shall be removed from the chamber and allowed to cool under normal atmospheric conditions for a minimum of 4 hours.

2.9 OPERATING LIFE CONDITIONS

The conditions shall be as specified for Burn-in.

APPENDIX A

AGREED DEVIATIONS FOR VISHAY SFERNICE (F)

Items Affected	Description of Deviations
Deviations from Generic Specification: Special In-Process Controls (Chart F2) Screening Tests (Chart F3) Qualification and Periodic Tests (Chart F4)	 Para. 5.2.1, Dimension Check: Guaranteed but not tested. Para. 8.2, Non-Linearity: Not applicable. Para. 8.15, Permanence of Marking: Not applicable.
Deviations from Generic Specification Screening Tests (Chart F3)	For Variants 09 to 12, when failure rate level qualification approval in accordance with ESCC Basic Specification No. 2xxxx has been granted, the following deviations shall apply. Para. 8.1 (& Para. 2.3 herein), Overload: Resistance and Change in Resistance shall be measured on a GONOGO basis, in accordance with Room Temperature Electrical Measurements in the Detail Specification, both before and after the test. Change in Resistance shall be related to the initial measurements. The limit for Change in Resistance shall be: $\Delta R_A/R_A=\pm(0.05 +0.05\Omega \times 100/R_n)\%$ max Para. 8.4 (& Para. 2.8 herein), Burn-in: Not applicable.